

What is claimed is:

1. A micropatterned thermosensor, in particular an infrared sensor, including a supporting body and at least one thermocouple located thereon, which has a first material and a second material which form at least in a point-wise manner, at least one thermal contact with each other, wherein the first and/or the second material (13, 14) are at least regionally designed in the form of a meander-shaped or undulating-type circuit trace (15, 16) and run on the supporting body (12).

2. The micropatterned thermosensor as recited in Claim 1,

wherein the first material (13) and the second material (14) run at least substantially side-by-side in the form of circuit traces (15, 16) and are electrically insulated from one another, with the exception of thermal contacts (10, 11), or run over one another at least regionally in the form of circuit traces (15, 16), and are electrically insulated from one another, with the exception of thermal contacts (10, 11).

3. The micropatterned thermosensor as recited in Claim 1 or 2,

wherein the thermocouple (20) includes a plurality of thermal contacts (10, 11), which are configured in the manner of a thermal chain or thermal column, at least two of the thermal contacts (10, 11) being exposed to different temperatures (T_1 , T_2).

4. The micropatterned thermosensor as recited in Claim 3, wherein a second thermal contact (11) is provided, which is exposed to a second temperature (T_2) to be detected or measured, and a first thermal contact (10) is provided, which is exposed to a first temperature (T_1) that is to be kept constant or at least approximately constant; it further being provided that the first temperature (T_1) is detectable via an additional measuring device.

5. The micropatterned thermosensor as recited in Claim 4, wherein the measuring device includes a part of one of the circuit traces (15, 16), situated in a vicinity of the first thermal contact (10), or of one of the conductors (17) or includes a reference circuit trace as sensitive component, situated in a vicinity of the first thermal contact (10), as well as evaluation means for determining a temperature-dependent, electrical resistance of the part of the circuit trace (15, 16), the conductor (17) or the reference circuit trace.

6. The micropatterned thermosensor as recited in at least one of the preceding claims, wherein the first and/or the second material (13, 14) is a material having low thermal conductivity.

7. The micropatterned thermosensor as recited in at least one of the preceding claims, wherein the first and the second material (13, 14) are selected from the platinum, gold, lead tellurides, aluminum, titanium, polysilicon, doped polysilicon, polysilicon-germanium or doped polysilicon-germanium group.

8. The micropatterned thermosensor as recited in Claim 7, wherein the second material (14) is platinum, and the first material (13) is doped or undoped polysilicon-germanium.

9. The micropatterned thermosensor as recited in Claim 5 or 8, wherein the part of the circuit trace (15, 16), the conductor (17) or the reference circuit trace is a platinum circuit trace.

10. The micropatterned thermosensor, in particular the infrared sensor, including a supporting body and at least one thermocouple located thereon, having a first material and a

second material, which form at least in a point-wise manner at least one thermal contact with each other, wherein the second material (14) is platinum or aluminum and the first material (13) is doped or undoped polysilicon-germanium.

11. The micropatterned thermosensor as recited in Claim 10,

wherein the first and/or the second material (13, 14) are designed at least regionally in the form of a meander-shaped or undulating-type circuit trace (15, 16) and run(s) on the supporting body (12).

12. The micropatterned thermosensor as recited in Claim 10 or 11,

wherein the thermocouple (20) has a plurality of thermal contacts (10, 11), which are configured in the manner of a thermal chain or a thermal column, at least two of the thermal contacts (10, 11) being exposed to different temperatures (T_1 , T_2).